

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2005-015885

(43)Date of publication of application : 20.01.2005

(51)Int.Cl.

C23C 18/31
C23F 1/08
G01B 21/08
H01L 21/288
H01L 21/3205

(21)Application number : 2003-185061

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(22)Date of filing : 27.06.2003

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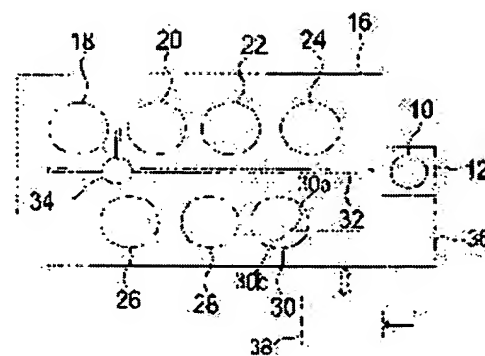
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(54) SUBSTRATE PROCESSING METHOD AND APPARATUS

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a substrate processing method and an apparatus which can measure and monitor the thickness and/or properties of a thin film formed on a substrate as needed, and quickly correct a deviation in the process conditions, and which can therefore stably provide products of constant quality.

SOLUTION: When a substrate with a metal and an insulating material exposed on its surface is subjected to processing for selectively or preferentially changing the film thickness of the metal portion with the exposed surface of the metal as a reference plane, a change in the film thickness and/or a change in film property of the metal portion during and/or immediately after processing are measured with a film thickness sensor 30a and/or a film property sensor 30b, and on the basis of the results of measurement, the state of the film processing is monitored to adjust the processing conditions.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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